

Inventor: Michael E. Thomas et al.

Title: Homogenous Solid Solution Alloys for Sputter-Deposited Thin Films

Assignee: Honeywell International Inc.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

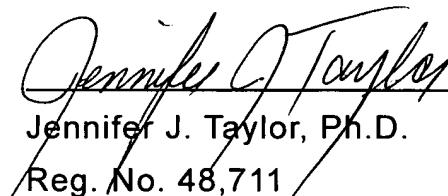
References – See Attached Form PTO-1449

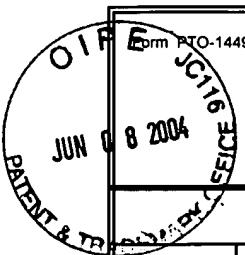
The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. No admission is made regarding whether any of the submitted references is prior art. Copies of the references are attached with the exception of U.S. patents and published applications (1276 Off. Gaz. Pat. Off. 55, 05 August 2003).

Respectfully submitted,

Dated: June 8, 2004

By:


Jennifer J. Taylor, Ph.D.
Reg. No. 48,711



U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE					ATTY. DOCKET NO. H0003933-US		SERIAL NO. 10/665,128	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					APPLICANT Michael E. Thomas et al.			
					FILING DATE September 22, 2003		GROUP 1742	
U.S. PATENT DOCUMENTS								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA	4,895,770	01-1990	Schintmeister et al.				
	AB	6,396,207	05-2002	Hasegawa et al.				
	AC	6,210,634	04-2001	Ishigami et al.				
	AD							
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
	AL							
FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
	AM	JP08255912	01-1996	Japan			<input checked="" type="checkbox"/> Yes	<input type="checkbox"/> No
	AN						<input checked="" type="checkbox"/> X	<input type="checkbox"/>
	AO						<input type="checkbox"/>	<input type="checkbox"/>
	AP						<input type="checkbox"/>	<input type="checkbox"/>
	AQ						<input type="checkbox"/>	<input type="checkbox"/>
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
	AR							
	AS							
	AT							
EXAMINER				DATE CONSIDERED				
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>								

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